~~WHAT IS CLAIMED IS:~~PATENT CLAIMS

1. A method of manufacturing, on a ~~waver~~wafer scale, a plurality of optical devices being camera modules with a sensor module or being optical modules for camera modules with a sensor module, wherein a camera module with a sensor module may be identified with a camera, and wherein each of the cameras has sub-cameras for capturing sub-images of red, green, or blue color, the optical devices each defining an optical path, the method comprising the steps of:

   - providing a first wafer scale substrate comprising a pattern of lenses and comprising a wavelength selective filter that is patterned to comprise a plurality of filter sections~~,~~ which are color filters of the sub-cameras for capturing sub-images of red, green, or blue color;

   - providing a wafer scale spacer with a plurality of holes arranged in a hole pattern that corresponds to the pattern of lenses;

   - stacking the first substrate and the spacer on each other with the holes and the lenses being aligned, and with the filter sections being arranged and dimensioned so that the respective optical path traverses the respective filter section, the step of stacking yielding a wafer scale stack, and

   - separating the wafer scale stack into the optical devices.

2. The method according to claim 1, comprising, prior to the step of separating the wafer scale stack, the further step of providing a second wafer scale substrate and stacking the second wafer scale substrate and the spacer on each other.

3. The method according to claim 2, wherein the second wafer scale substrate is a transparent optical substrate with an array of optical elements.

corresponding to a propagation direction along the optical beam path, each spaced from filter sections of the other optical devices.

~~11. The method according to any one of the previous claims, wherein the filter is an infrared filter and wherein the filter sections are infrared filter sections.~~

11. ~~12.~~A wafer scale optical substrate, comprising a substrate body of an optically transparent material with two essentially plane parallel surfaces, and further comprising a wavelength selective filter applied to a first one of the surfaces, the filter comprising a plurality of filter sections that are mutually spaced from each other and are arranged in an array and which are color filters of sub-cameras for capturing sub-images of red, green, or blue color.

12. ~~13.~~A camera~~,~~ having sub-cameras for capturing sub-images of red, green, or blue color, the camera comprising a sensor module and an optical system defining an optical axis, the camera comprising at least one spacer, and at least one transparent substrate of the optical system, the substrate carrying an optical element, wherein the sensor module, the spacer, and the substrate with the optical element are stacked vertically with respect to the optical axis, wherein at least one filter adheres to the substrate, wherein the substrate has a first area perpendicular to the optical axis, wherein the filter has a second area that is smaller than the first area and wherein an optical path defined by the optical system and the sensor module traverses the filter, wherein the filter comprises a plurality of filter sections which are color filters of the sub-cameras for capturing sub-images of red, green, or blue color.

13. ~~14.~~The camera according to claim ~~13~~12, wherein the optical system further comprises an aperture formed by a hole in a non-transparent layer.

14. ~~15. The~~Method of manufacturing a color image, comprising the steps of

— capturing sub-images of red, green, and blue color, respectively, by means of a camera according to claim ~~13~~12 or ~~14~~claim 13, wherein ~~the filter is an infrared filter.~~said sub-images are captured by means of the sub-cameras of said camera; and

— combining the sub-images to the color image.